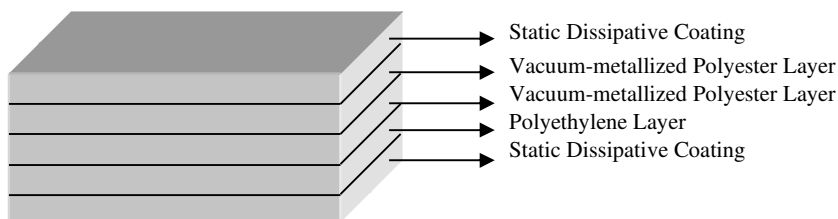


PRODUCT SPECIFICATION
DOCUMENT CONTROL NO.: DY3008-652 REV. J**DY3008-652 Moisture Barrier Material****PRODUCT** : Moisture Barrier Film (Bag)**DESCRIPTION** : -652 is 3.6mil, heat sealable, electrostatic protective, moisture protective multi-layer laminated material for ESD safe and moisture barrier packaging. DY3800 denotes “cleanroom grade” while DY3700 refer to Ziplock bags made using -652 material. Meets ANSI/ESD S20.20, Packaging standard ANSI/ESD S541 and ANSI/ESD S11.4 Level 2.**CONSTRUCTION**: (from outer to inner layer in bag form)

PHYSICAL PROPERTIES	TEST METHOD	TYPICAL VALUE
Total Thickness	ASTM D-374	3.6 mils $\pm$ 10%
Tensile Strength	ASTM D-882-91, Method A	> 7,000 psi (MD) > 7,000 psi (TD)
Tear Strength	ASTM-D-1004-94 Notched	> 2.4 lbs (MD) > 2.7 lbs (TD)
Puncture Strength	MIL-STD-3010, 2065	$\geq$ 20 lbs
Heat Seal Strength	ASTM D-882-91	$\geq$ 14 lbs/in. width
MVTR (at 90% RH, /100 in ² /24 hrs)	ASTM F-1249	$\leq$ 0.02 gm

Static
Control

Cleanroom

Wafer
Handling &
SingulationElectronics
/ Dry
PackagingIC Mold
Cleaning
Compound

MIM/ CIM

Tapes
& ReelsOther
Industrial
Tools &
Equipment

PRODUCT SPECIFICATION
DOCUMENT CONTROL NO.: DY3008-652 REV. J

ELECTRICAL PROPERTIES	TEST METHOD	TYPICAL VALUE
Surface Resistance – Outer Surface	ANSI/ESD STM-11.11 @ 12% R.H.	$\geq 1.0 \times 10^4$ to $< 1.0 \times 10^{11} \Omega$
Surface Resistance – Inner Surface	ANSI/ESD STM-11.11 @ 12% R.H.	$\geq 1.0 \times 10^4$ to $< 1.0 \times 10^{11} \Omega$
Discharge Shielding	ANSI/ESD STM-11.31 @ 12% R.H.	$< 10 \text{ nJ (*)}$

(*) Certain bag configurations do not meet such criteria

HEAT SEAL CONDITIONS : 250°F -375°F, 0.8-3.5 sec, 30-70 PSI.

The values shown above were developed from random samples taken from production material. We believe them to be typical for the product. Actual values may vary somewhat from those depicted here and Dou Yee Enterprises makes no warranty, expressed or implied, as to the suitability of these materials for any specific use. Customers should determine product suitability based upon their own criteria and further qualification process.

Date : December 2021



Static Control



Cleanroom



Wafer Handling & Singulation



Electronics / Dry Packaging



IC Mold Cleaning Compound



MIM/ CIM



Tapes & Reels



Other Industrial Tools & Equipment